Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.35 EP)
Lead Count	16
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.26E-02	86.91	869100	31.67	316718
Thermosets	Epoxy & Phenol Resin	Proprietary	1.86E-03	12.78	127800	4.66	46573
Other inorganic materials	Carbon black	1333-86-4	4.51E-05	0.31	3100	0.11	1130
Subtotal			1.46E-02	100.00	1000000	36.44	364421

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.21 E-02	97.5	975000	55.26	552623
Copper & its alloys	Iron	7439-89-6	5.32 E-04	2.35	23500	1.33	13320
Copper & its alloys	Zinc	7440-66-6	2.72 E-05	0.12	1200	0.07	680
Copper & its alloys	Phosphorus	7723-14-0	6.79 E-06	0.03	300	0.02	170
Subtotal			2.26 E-02	100.00	1000000	56.68	566793

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.10 E-04	100.0	1000000	1.03	10269

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	7.30 E-04	100.0	1000000	1.83	18284

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.56 E-04	99.0	990000	0.89	8926
Precious metals	Palladium	7440-05-3	3.60 E-06	1.0	10000	0.01	90
Subtotal			3.60 E-04	100.0	1000000	0.90	9017

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.40 E-04	100.0	1000000	2.35	23543

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.28 E-04	73.40	734000	0.57	5699
Thermoset	Epoxy Resin	Proprietary	5.69 E-05	18.35	183500	0.14	1425
Other inorganic materials	Metal oxide	Proprietary	8.53 E-06	2.75	27500	0.02	214
Others	Curing and hardening agent	Proprietary	8.53 E-06	2.75	27500	0.02	214
Other organic materials	Gamma Butyrolactone	96-48-0	8.53 E-06	2.75	27500	0.02	214
Subtotal			3.10 E-04	100.0	972500	0.76	7764

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.99 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES